

50V~1000V 1.0A SMA

Surface Mount Ultrafast Recovery Rectifier,Reverse Voltage:50 to1000V,Forward Current:1.0A, SMA package.

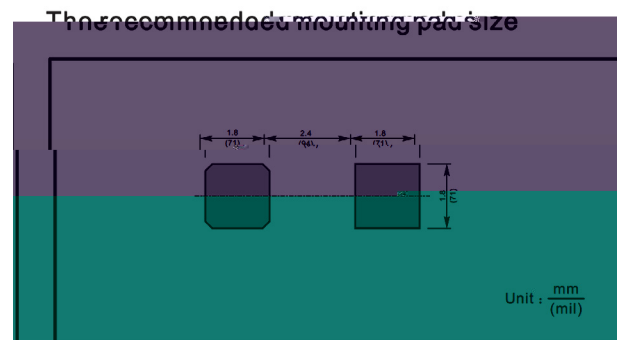
2011/65/EU RoHS

Glass Passivated Chip Junction High efficiency Lead free in comply with EU R HS 2011/65/EU directives For surface mounted applications,HF product.

General purpose.



PIN	DESCRIPTION
1	Cathode
2	Anode



See Marking Instructions.

Note:

Parameter	Symbol	Rating							Unit
		US1A	US1B	US1D	US1G	US1J	US1K	US1M	

(1) P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areass.

(2) Measured at 1 MHz and applied reverse voltage of 4 V D.C.

Parameter	Symbol	Test condition	Rating							Unit
			US1A	US1B	US1D	US1G	US1J	US1K	US1M	
Maximum Instantaneous Forward Voltage	V _F	I _F =1.0A	1.0			1.3	1.65			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I _R	T _a =25	5.0							uA
		T _a =125	100							
Maximum Reverse Recovery Time	T _{rr}	I _F =0.5A I _R =1.0A I _{rr} =0.25A	50				75			ns

Fig.1 Forward Current Derating Curve

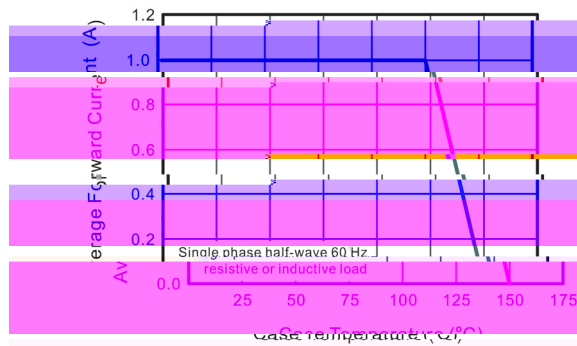


Fig.2 Typical Reverse Characteristics

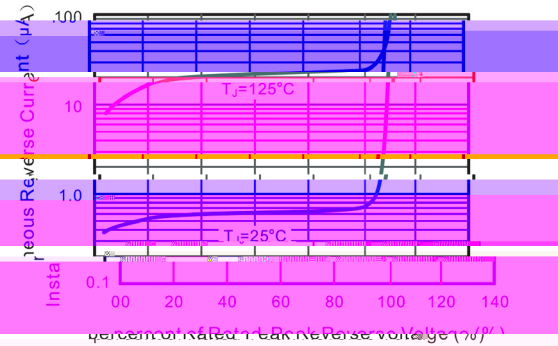


Fig.3 Typical Forward Characteristics

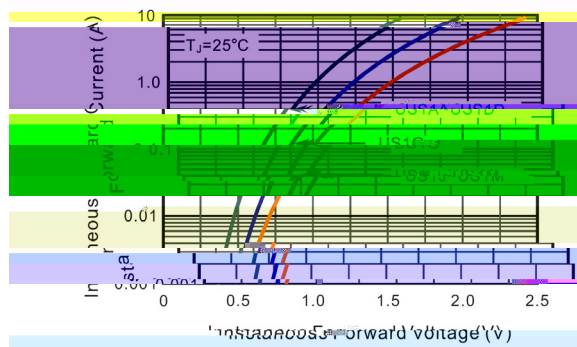


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current

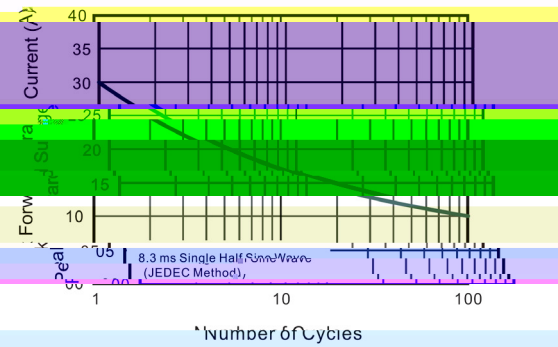


Fig.5- Typical Transient Thermal Impedance

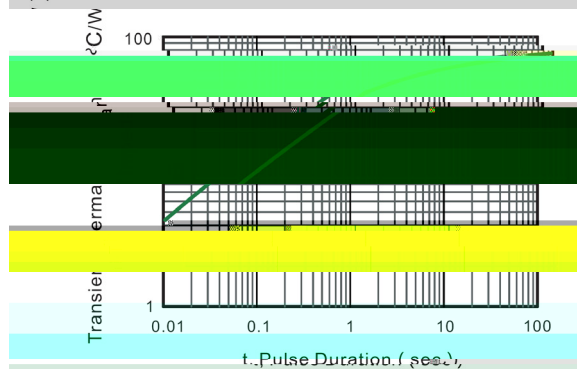
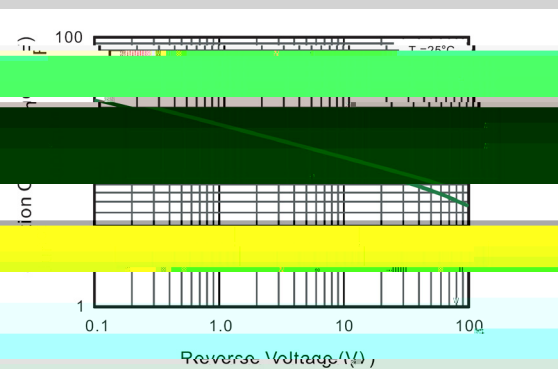


Fig.6 Typical Junction Capacitance



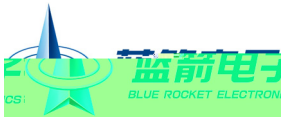


US1A

Note:

US1A Product Type Code
 Lot No. Code, code change with Lot No

Type number	Marking code
US1A	US1A
US1B	US1B
US1D	US1D
US1G	US1G
US1J	US1J
US1K	US1K
US1M	US1M



Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

260±5

10±1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type	Units					Dimension (unit mm ³)		
SMA	5,000	2	10,000	7	70,000	13 ×12	336×336×40	380×335×366